## **LISTING OF CLAIMS:**

- 1. (Original) A system (10) for positioning components (20) of different thicknesses on a component platform (35), comprising:
  - a frame (15);

least partially received within the tool head (25).

- a tool head (25) connected to the frame (15), the tool head (25) being vertically movable;
- a retractable vacuum tube (26) receivable within the tool head (25); and a grasping assembly (60) which can be actuated to securely hold the vacuum tube (26) in a fixed position relative to the tool head (25) after the vacuum tube (26) has been at
- 2. (Original) The system of Claim 1, wherein the grasping assembly (60) comprises a bushing (61) which is movable along a collet (62).
- 3. (Original) The system of Claim 1, wherein the grasping assembly (60) further comprises a knob (63) for manually rotating the vacuum tube (26) about an axis extending longitudinally therethrough.
- 4. (Original) The system of Claim 1, wherein the frame (15) supports the tool head (25) such that the tool head (25) can be moved in X and Y directions.

- 5. (Original) The system of Claim 1, wherein the components (20) comprise electronic components.
- 6. (Original) The system of Claim 5, wherein the electronic components (20) comprise integrated circuit chips.
- 7. (Original) The system of Claim 1, wherein the component platform (35) comprises a printed circuit board.
- 8. (Withdrawn) A method of positioning a component on a target surface, comprising: positioning a tool head over the component, the tool head having a retractable vacuum tube extending downwardly therefrom;

lowering the tool head until the vacuum tube contacts an upper surface of the component and is pushed into a retracted position within the tool head;

securely holding the vacuum tube in a fixed position relative to the tool head after the vacuum tube has been pushed into the retracted position within the tool head;

lifting the tool head, thereby lifting the component with the vacuum tube; positioning the tool head over the target surface;

lowering the tool head such that a bottom surface of the component is positioned in contact with the target surface; and

releasing the component from the vacuum tube.

9. (Withdrawn) The method of Claim 8, wherein the vacuum tube is securely held in a fixed position relative to the tool head after the vacuum tube has been pushed into the retracted position within the tool head by:

moving a bushing along a collet within the tool head.

- 10. (Withdrawn) The method of Claim 8, wherein the component comprises an electronic component.
- 11. (Withdrawn) The method of Claim 10, wherein the electronic component comprises an integrated circuit chip.
- 12. (Withdrawn) The method of Claim 8, wherein the target surface comprises a printed circuit board.
- 13. (Withdrawn) The method of Claim 12, further comprising:

  placing the printed circuit board on a movable component platform; and
  positioning the printed circuit board by moving the component platform.
- 14. (Withdrawn) The method of Claim 13, wherein the component platform and the tool head are both attached to a frame of a positioning system, and wherein each of the component platform and the tool head are separately positionable in X and Y directions.